


MATERIAL DECLARATION SHEET



Package Type	PTVS2-(022C-026C-029C)-H			
Product Line	Semiconductor Products			
Compliance Date	26 th April 2022			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element (subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Encapsulation	Epoxy resin	0.1942	Amorphous Silica	60676-86-0	87.000	53.340761	55.281
				Solid Epoxy Resin 1	Proprietary	4.600	0.179802	
				Solid Epoxy Resin 2	Proprietary	4.490	0.153297	
				Phenol Resin	Proprietary	2.700	0.904592	
				Carbon Black	1333-86-4	0.700	0.332242	
				Crystalline Silica	14808-60-7	0.510	0.370213	
2	Leadframe	Copper Alloy	0.0618	Copper	7440-50-8	97.433	17.203720	17.588
				Iron	7439-89-6	2.350	0.364648	
				Phosphorus	7723-14-0	0.125	0.005764	
				Zinc	7440-66-6	0.082	0.011608	
				Lead	7439-92-1	0.010	0.002234	
3	Clip	Copper Alloy	0.0314	Copper	7440-50-8	95.485	8.452198	8.942
				Silver	7440-22-4	4.500	0.489026	
				Iron	7439-89-6	0.005	0.000389	
				Lead	7439-92-1	0.005	0.000560	
				Zinc	7440-66-6	0.003	0.000212	
				Phosphorous	7723-14-0	0.002	0.000046	
4	Electrodes	Copper Alloy	0.0302	Copper	7440-50-8	95.485	8.127209	8.599
				Silver	7440-22-4	4.500	0.470223	
				Iron	7439-89-6	0.005	0.000374	
				Lead	7439-92-1	0.005	0.000539	
				Zinc	7440-66-6	0.003	0.000203	
				Phosphorous	7723-14-0	0.002	0.000044	
5	Chip	Silicon	0.0167	Silicon	7440-21-3	90.650	4.317917	4.763
				Nickel	7440-02-0	5.403	0.257368	
				Aluminum	7429-90-5	3.815	0.181713	
				Gold	7440-57-5	0.132	0.006273	
6	Solder Paste	Solder	0.0141	Lead*	7439-92-1	92.500	3.786368	4.015
				Tin	7440-31-5	5.000	0.130487	
				Silver	7440-22-4	2.500	0.098312	
7	Terminal Finish	Tin	0.0029	Tin	7440-31-5	100.000	0.811658	0.812
		Total weight	0.3513					

* 7(a) Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)